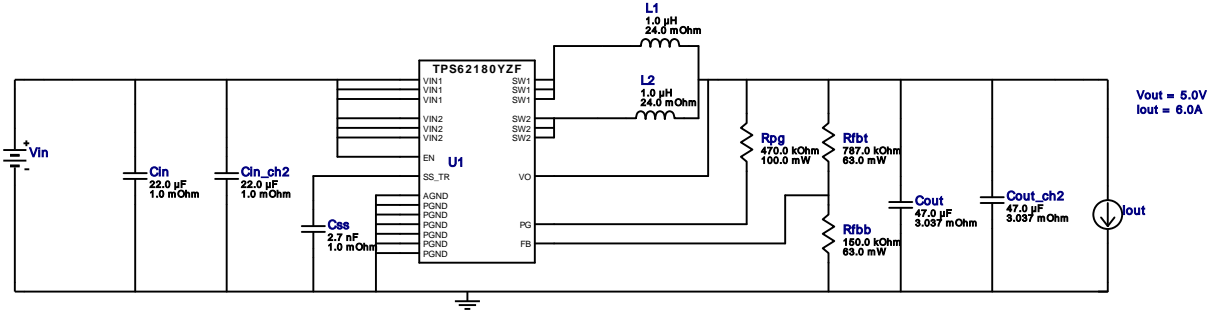


VinMin = 10.0V  
VinMax = 15.0V  
Vout = 5.0V  
Iout = 6.0A

Device = TPS62180YZFR  
Topology = Buck  
Created = 2023-07-11 02:40:49.695  
BOM Cost = \$3.43  
BOM Count = 11  
Total Pd = 2.63W

## WEBENCH® Design Report

Design : 1 TPS62180YZFR  
TPS62180YZFR 4V-15V to 3.30V @ 6A




### Design Alerts

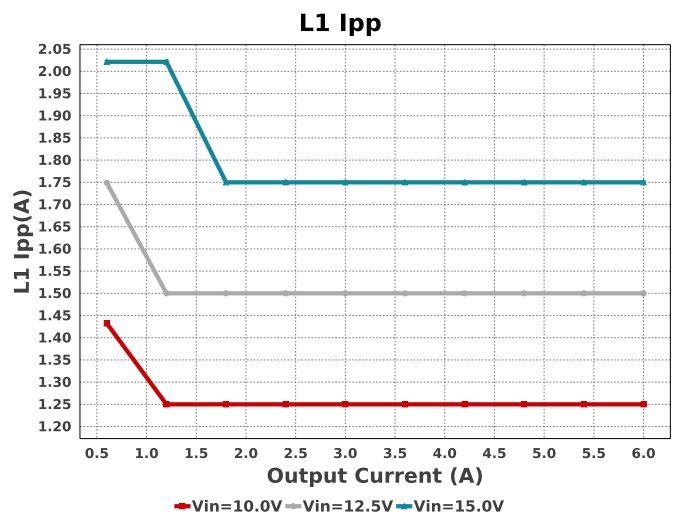
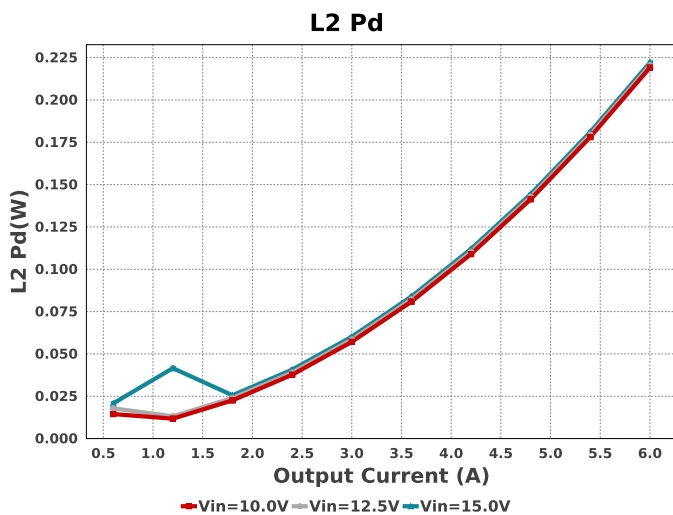
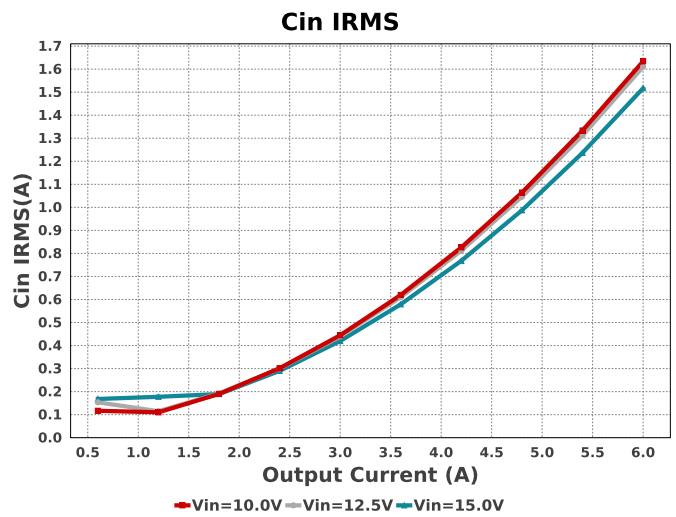
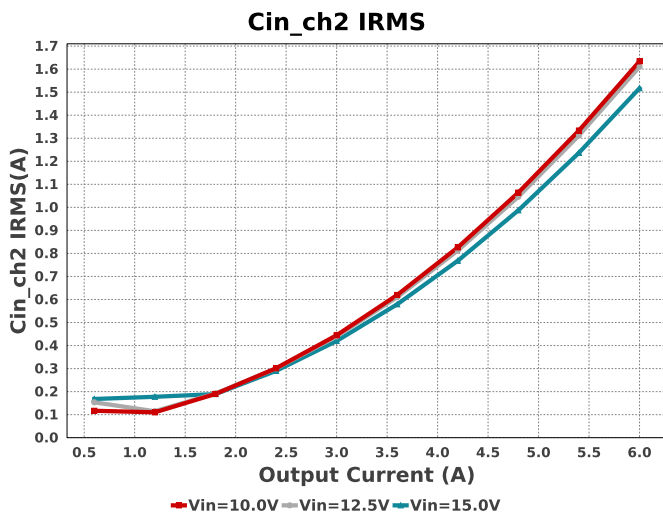
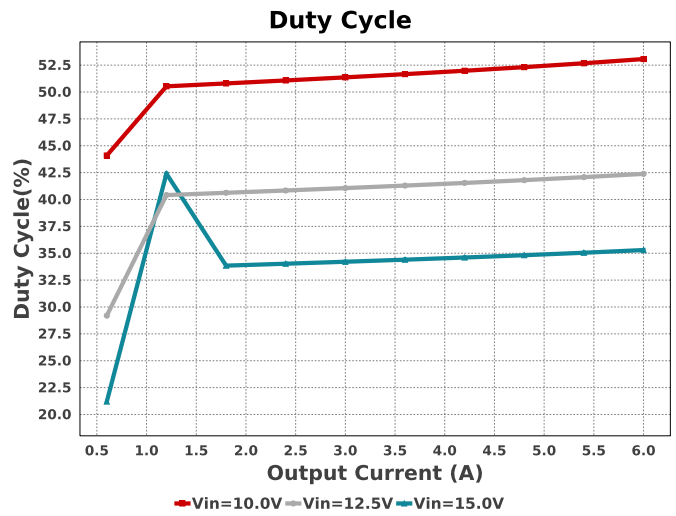
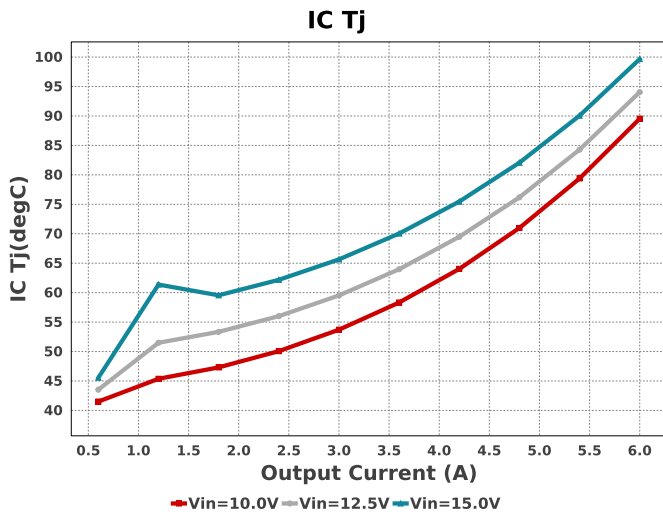
#### Component Selection Information

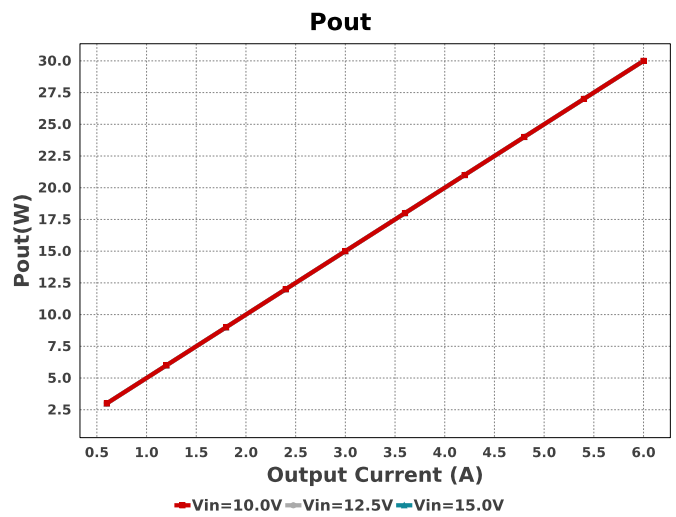
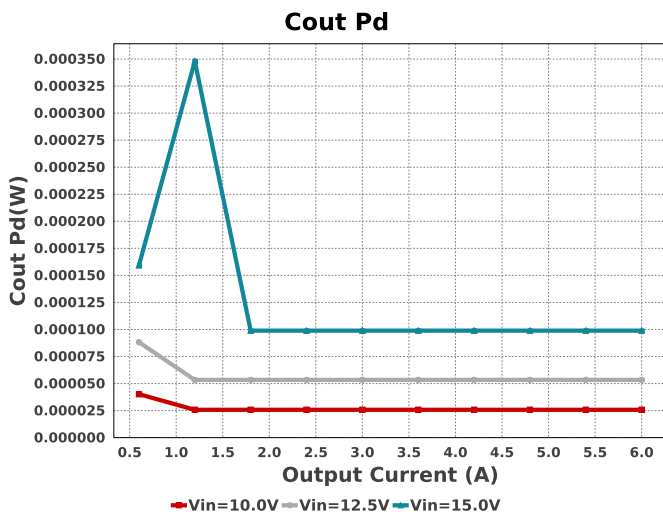
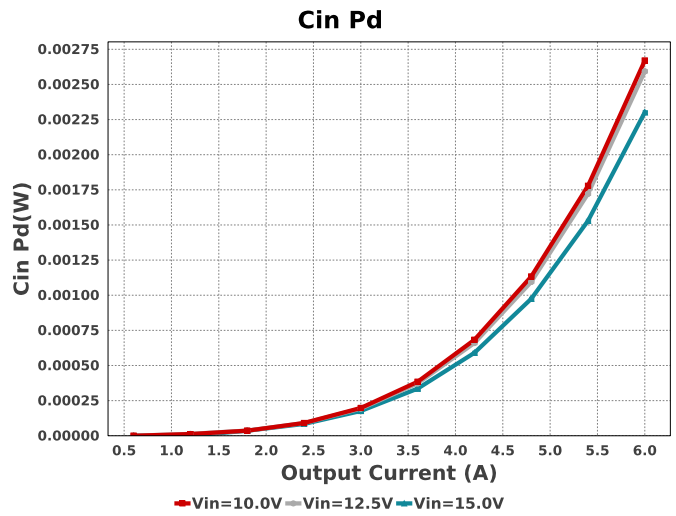
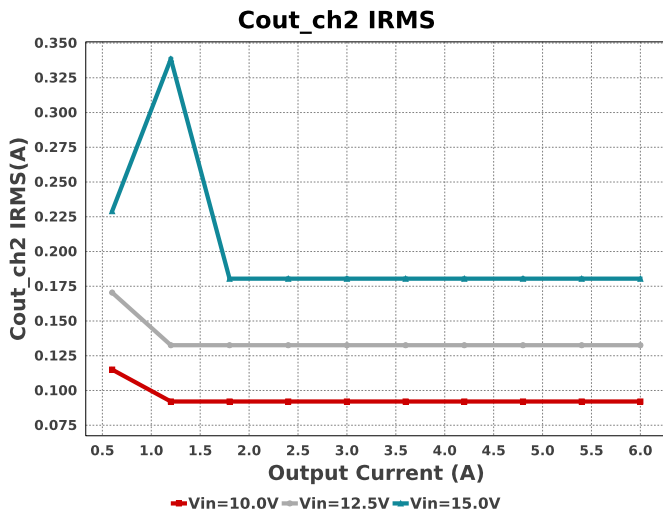
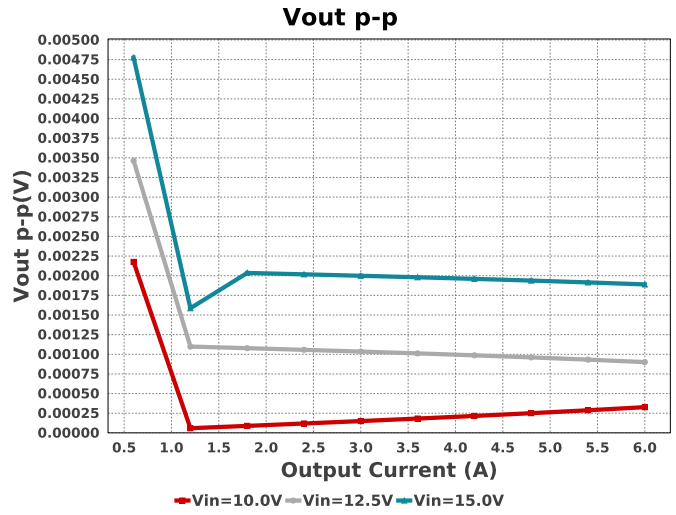
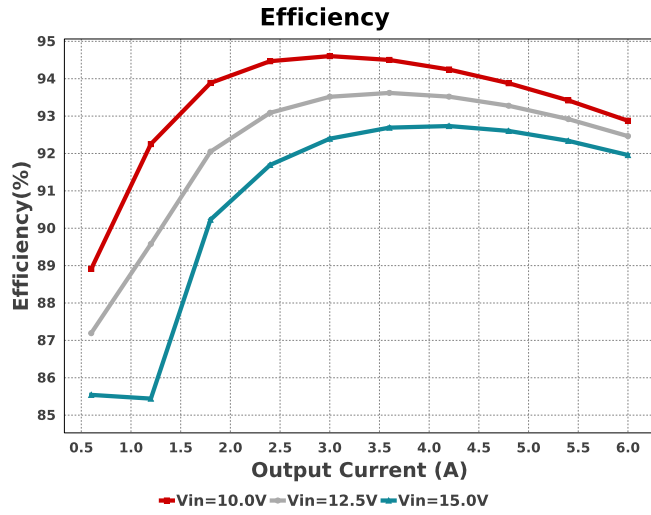
The TPS62180 is a dual-phase converter which allows a very small solution size for a 6A converter. This WEBENCH(R) model only supports two-inductor designs where the component pair (L1, L2), pair (Cin, Cin\_ch2) and pair (Cout, Cout\_ch2) are kept the same.

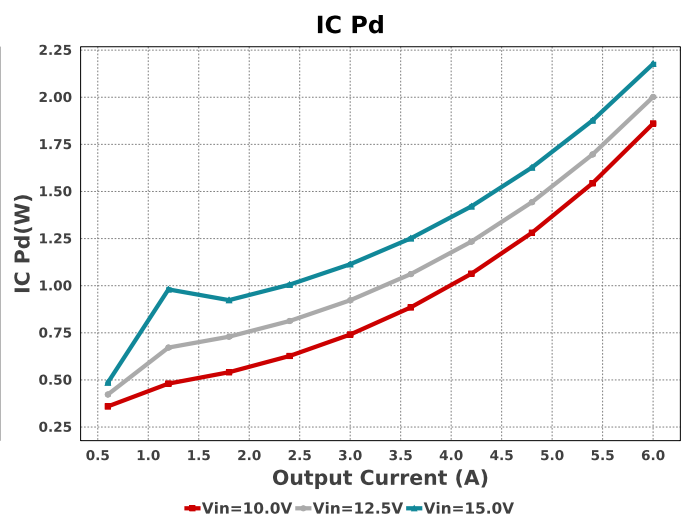
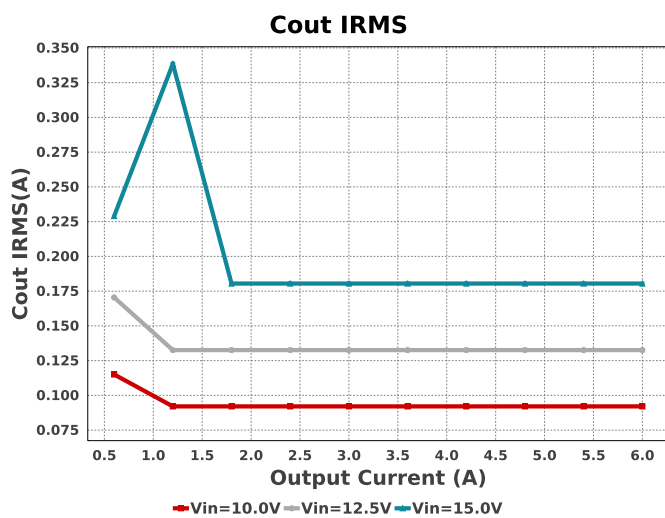
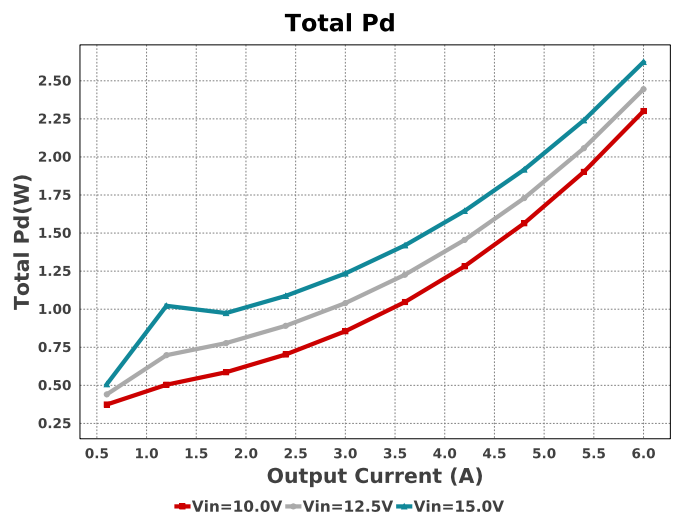
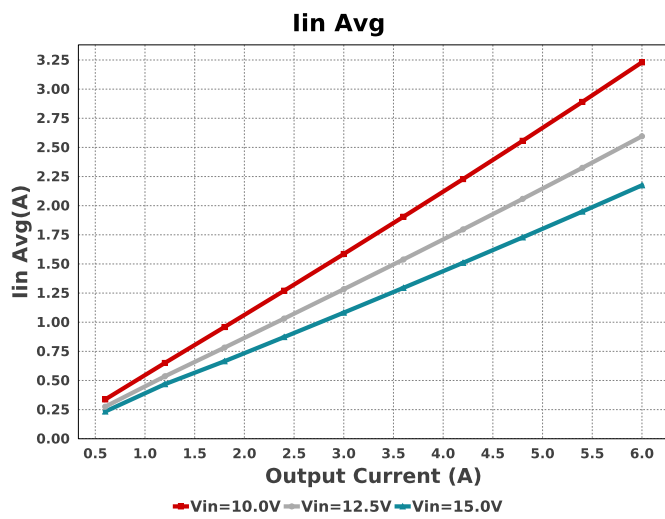
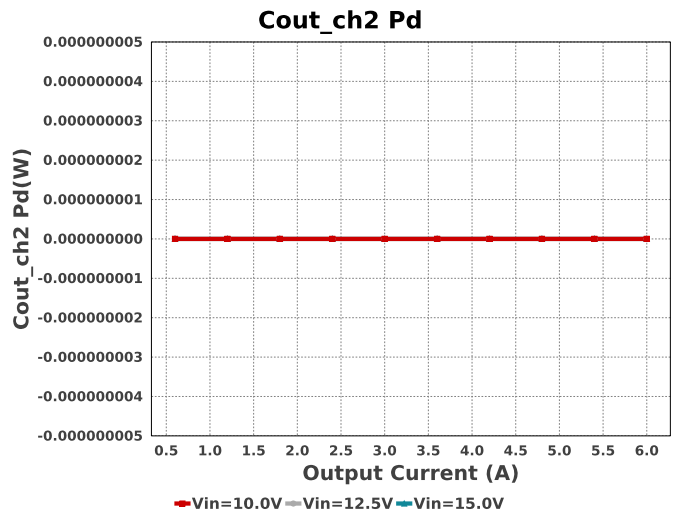
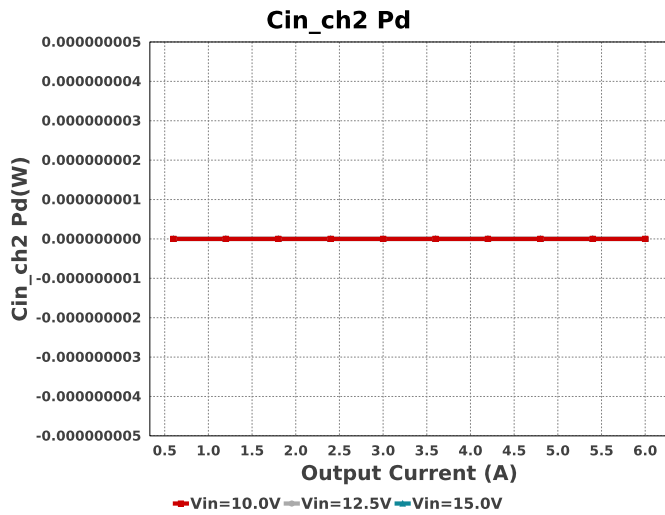
### Electrical BOM

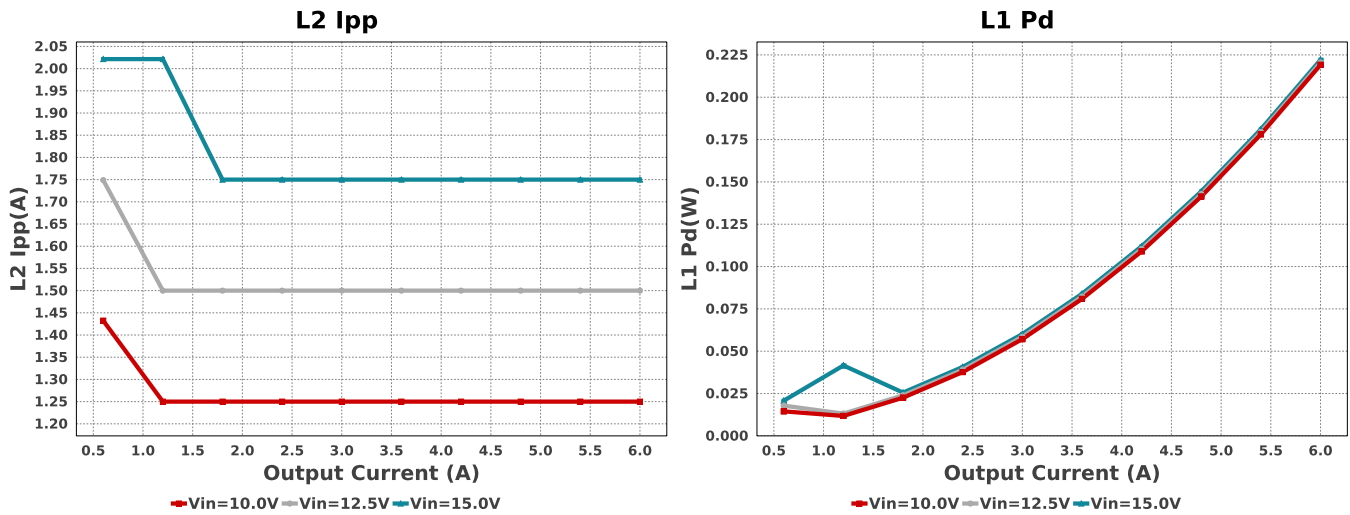
| Name     | Manufacturer | Part Number                          | Properties  | Qty | Price  | Footprint                      |
|----------|--------------|--------------------------------------|---|-----|--------|--------------------------------|
| Cin      | Taiyo Yuden  | TMK325B7226KMHP<br>Series= X7R       | Cap= 22.0 uF<br>ESR= 1.0 mOhm<br>VDC= 25.0 V<br>IRMS= 0.0 A       | 1   | \$0.31 | 1210_270 15 mm <sup>2</sup>    |
| Cin_ch2  | Taiyo Yuden  | TMK325B7226KMHP<br>Series= X7R       | Cap= 22.0 uF<br>ESR= 1.0 mOhm<br>VDC= 25.0 V<br>IRMS= 0.0 A       | 1   | \$0.31 | 1210_270 15 mm <sup>2</sup>    |
| Cout     | MuRata       | GRM32ER61C476KE15L<br>Series= X5R    | Cap= 47.0 uF<br>ESR= 3.037 mOhm<br>VDC= 16.0 V<br>IRMS= 4.59346 A | 1   | \$0.17 | 1210_280 15 mm <sup>2</sup>    |
| Cout_ch2 | MuRata       | GRM32ER61C476KE15L<br>Series= X5R    | Cap= 47.0 uF<br>ESR= 3.037 mOhm<br>VDC= 16.0 V<br>IRMS= 4.59346 A | 1   | \$0.17 | 1210_280 15 mm <sup>2</sup>    |
| Css      | MuRata       | GRM188R71E272KA01D<br>Series= X7R    | Cap= 2.7 nF<br>ESR= 1.0 mOhm<br>VDC= 25.0 V<br>IRMS= 0.0 A        | 1   | \$0.01 | 0603 5 mm <sup>2</sup>         |
| L1       | Vishay-Dale  | IHLP1212BZER1R0M11                   | L= 1.0 uH<br>24.0 mOhm  | 1   | \$0.63 | IHLP-1212BZ 19 mm <sup>2</sup> |
| L2       | Vishay-Dale  | IHLP1212BZER1R0M11                   | L= 1.0 uH<br>24.0 mOhm  | 1   | \$0.63 | IHLP-1212BZ 19 mm <sup>2</sup> |
| Rfbb     | Vishay-Dale  | CRCW0402150KFKED<br>Series= CRCW..e3 | Res= 150.0 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0%              | 1   | \$0.01 | 0402 3 mm <sup>2</sup>         |
| Rfbb     | Vishay-Dale  | CRCW0402787KFKED<br>Series= CRCW..e3 | Res= 787.0 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0%              | 1   | \$0.01 | 0402 3 mm <sup>2</sup>         |
| Rpg      | Yageo        | RC0603FR-07470KL<br>Series= ?        | Res= 470.0 kOhm<br>Power= 100.0 mW<br>Tolerance= 1.0%             | 1   | \$0.01 | 0603 5 mm <sup>2</sup>         |

| Name | Manufacturer      | Part Number  | Properties | Qty | Price  | Footprint  |
|------|-------------------|--------------|------------|-----|--------|--|
| U1   | Texas Instruments | TPS62180YZFR | Switcher   | 1   | \$1.17 |  YZF0024AMAM 13 mm <sup>2</sup> |









## Operating Values

| #   | Name          | Value                 | Category  | Description  |
|-----|---------------|-----------------------|-----------|--|
| 1.  | Cin IRMS      | 1.517 A               | Capacitor | Input capacitor RMS ripple current                                 |
| 2.  | Cin Pd        | 2.302 mW              | Capacitor | Input capacitor power dissipation                                  |
| 3.  | Cin_ch2 IRMS  | 1.517 A               | Capacitor | Input Capacitor Cin2 RMS Ripple Current                            |
| 4.  | Cin_ch2 Pd    | 2.302 mW              | Capacitor | Average Power Dissipation in the Input Capacitor Cin2              |
| 5.  | Cout IRMS     | 180.46 mA             | Capacitor | Output capacitor RMS ripple current                                |
| 6.  | Cout Pd       | 98.902 μW             | Capacitor | Output capacitor power dissipation                                 |
| 7.  | Cout_ch2 IRMS | 180.46 mA             | Capacitor | Output capacitor2 RMS ripple current                               |
| 8.  | Cout_ch2 Pd   | 98.902 μW             | Capacitor | Output capacitor2 power dissipation                                |
| 9.  | IC Ipk        | 3.875 A               | IC        | Max rated switch current in IC                                     |
| 10. | IC Iq Pd      | 1.5 μW                | IC        | IC Iq Pd   |
| 11. | IC Pd         | 2.177 W               | IC        | IC power dissipation   |
| 12. | IC Tj         | 99.667 degC           | IC        | IC junction temperature  |
| 13. | IC Tolerance  | 8.0 mV                | IC        | IC Feedback Tolerance  |
| 14. | ICThetaJA     | 32.0 degC/W           | IC        | IC junction-to-ambient thermal resistance                          |
| 15. | Iin Avg       | 2.175 A               | IC        | Average input current  |
| 16. | L1 Ipp        | 1.75 A                | Inductor  | Peak-to-peak inductor ripple current                               |
| 17. | L1 Pd         | 222.13 mW             | Inductor  | Inductor power dissipation   |
| 18. | L2Ipp         | 1.75 A                | Inductor  | Peak-to-peak inductor ripple current                               |
| 19. | L2 Pd         | 222.13 mW             | Inductor  | Inductor power dissipation   |
| 20. | Cin Pd        | 2.302 mW              | Power     | Input capacitor power dissipation                                  |
| 21. | Cin_ch2 Pd    | 2.302 mW              | Power     | Average Power Dissipation in the Input Capacitor Cin2              |
| 22. | Cout Pd       | 98.902 μW             | Power     | Output capacitor power dissipation                                 |
| 23. | Cout_ch2 Pd   | 98.902 μW             | Power     | Output capacitor2 power dissipation                                |
| 24. | IC Pd         | 2.177 W               | Power     | IC power dissipation   |
| 25. | L1 Pd         | 222.13 mW             | Power     | Inductor power dissipation   |
| 26. | L2 Pd         | 222.13 mW             | Power     | Inductor power dissipation   |
| 27. | Total Pd      | 2.626 W               | Power     | Total Power Dissipation  |
| 28. | BOM Count     | 11                    | System    | Total Design BOM count   |
| 29. | Duty Cycle    | 35.297 %              | System    | Duty cycle   |
| 30. | Efficiency    | 91.951 %              | System    | Steady state efficiency  |
| 31. | FootPrint     | 126.0 mm <sup>2</sup> | System    | Total Foot Print Area of BOM components                            |
| 32. | Frequency     | 1.905 MHz             | System    | Switching frequency  |
| 33. | Iout          | 6.0 A                 | System    | Iout operating point   |
| 34. | Mode          | CCM                   | System    | Conduction Mode  |
| 35. | Pout          | 30.0 W                | System    | Total output power   |
| 36. | Total BOM     | \$3.43                | System    | Total BOM Cost   |
| 37. | Vin           | 15.0 V                | System    | Vin operating point  |
| 38. | Vout          | 5.0 V                 | System    | Operational Output Voltage   |
| 39. | Vout Actual   | 4.997 V               | System    | Vout Actual calculated based on selected voltage divider resistors |

| #   | Name           | Value    | Category           | Description  |
|-----|----------------|----------|--------------------|--|
| 40. | Vout Tolerance | 2.714 %  | System Information | Vout Tolerance based on IC Tolerance (full load) and voltage divider resistors if applicable |
| 41. | Vout p-p       | 2.615 mV | System Information | Peak-to-peak output ripple voltage   |

## Design Inputs

| Name    | Value    | Description            |
|---------|----------|------------------------|
| Iout    | 6.0      | Maximum Output Current |
| VinMax  | 15.0     | Maximum input voltage  |
| VinMin  | 10.0     | Minimum input voltage  |
| Vout    | 5.0      | Output Voltage         |
| base_pn | TPS62180 | Base Product Number    |
| source  | DC       | Input Source Type      |
| Ta      | 30.0     | Ambient temperature    |

## WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of  $C_{in}$  and  $C_{out}$ , and the inductance and DC resistance of  $L1$  before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 10.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to  $V_{in}$  and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from  $V_{out}$  and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between  $V_{in}$  and GND, a load is connected between  $V_{out}$  and GND and a current meter is connected in series between  $V_{out}$  and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



### Design Assistance

1. Master key : 8D06C45BDA54575D0ABDC1D23455A5FE[v1]
2. **TPS62180** Product Folder : <http://www.ti.com/product/TPS62180> : contains the data sheet and other resources.

**Important Notice and Disclaimer**

TI provides technical and reliability data (including datasheets), design resources (including reference designs), application or other design advice, web tools, safety information, and other resources AS IS and with all faults, and disclaims all warranties. These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Providing these resources does not expand or otherwise alter TI's applicable Terms of Sale or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with TI products.